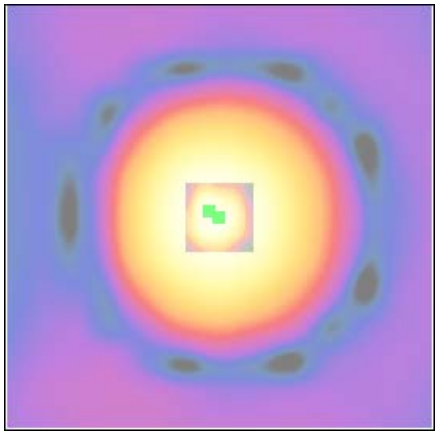
CELL BC-10

Test Laboratory: Comptest/Kyocera

FCC_E4233_TCoil_CELL 476 Z
Communication System: CDMA_Tri_BC0&10, Frequency: 817.9 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: $\sigma = 0$ mho/m, $\varepsilon_r = 1$; $\rho = 0$ kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/13/2011
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8̄ 1 deg C, Liquid T = 22.0̄ 1 deg C

General Scans_476/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.2 dB
ABM1 comp = -4.83 dB A/m
BWC Factor = 0.155979 dB
Location: 0, 0, 3.7 mm

General Scans_476/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.2 dB
ABM1 comp = -4.87 dB A/m
BWC Factor = 0.155979 dB
Location: 1.2, -0.8, 3.7 mm



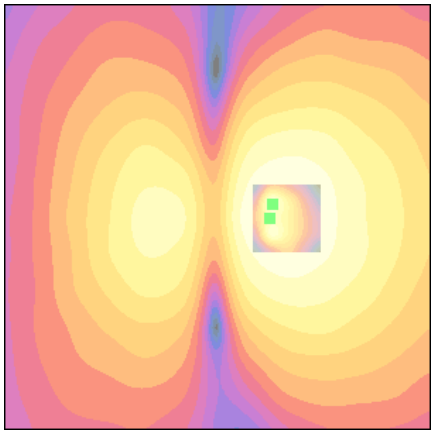
0 dB = 257.9

Test Laboratory: Comptest/Kyocera

FCC_E4233_TCoil_CELL 476 X
Communication System: CDMA_Tri_BC0&10, Frequency: 817.9 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/13/2011
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 ± 1 deg C, Liquid T = 22.0 ± 1 deg C

General Scans_476/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 40.5 dB
ABM1 comp = -13.7 dB A/m
BWC Factor = 0.155979 dB
Location: -6.2, 0, 3.7 mm

General Scans_476/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 40.9 dB
ABM1 comp = -13.6 dB A/m
BWC Factor = 0.155979 dB
Location: -6.5, -1.6, 3.7 mm



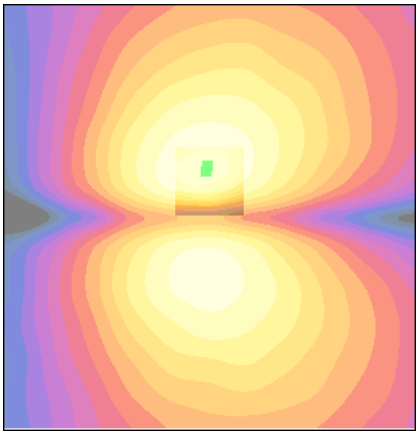
0 dB = 106.3

Test Laboratory: Comptest/Kyocera

FCC_E4233_TCoil_CELL 476 Y
Communication System: CDMA_Tri_BC0&10, Frequency: 817.9 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/13/2011
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 ± 1 deg C, Liquid T = 22.0 ± 1 deg C

General Scans_476/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 44.7 dB
ABM1 comp = -13.1 dB A/m
BWC Factor = 0.155979 dB
Location: 0.4, -5.4, 3.7 mm

General Scans_476/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 45.2 dB
ABM1 comp = -12.5 dB A/m
BWC Factor = 0.155979 dB
Location: 0.2, -6, 3.7 mm



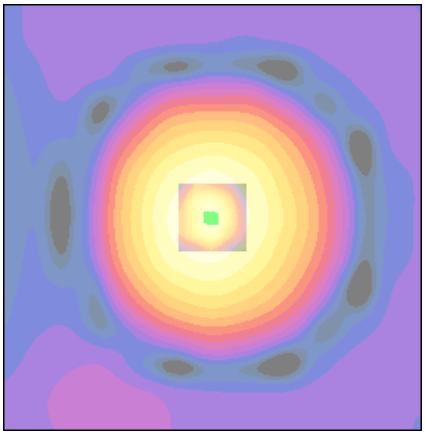
0 dB = 171.9

Test Laboratory: Comptest/Kyocera

FCC_E4233_TCoil_CELL 580 Z
Communication System: CDMA_Tri_BC0&10, Frequency: 820.5 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: $\sigma = 0$ mho/m, $\varepsilon_r = 1$; $\rho = 0$ kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/13/2011
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 ± 1 deg C, Liquid T = 22.0 ± 1 deg C

General Scans_580/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.1 dB
ABM1 comp = -5.05 dB A/m
BWC Factor = 0.155979 dB
Location: 0.4, 0, 3.7 mm

General Scans_580/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.6 dB
ABM1 comp = -4.68 dB A/m
BWC Factor = 0.155979 dB
Location: 0, 0.2, 3.7 mm



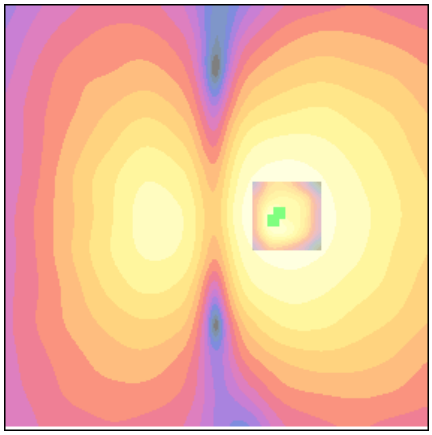
0 dB = 252.9

Test Laboratory: Comptest/Kyocera

FCC_E4210_TCoil_CELL 580 X
Communication System: CDMA_Tri_BC0&10, Frequency: 820.5 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/13/2011
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 ± 1 deg C, Liquid T = 22.0 ± 1 deg C

General Scans_580/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 40.7 dB
ABM1 comp = -14.3 dB A/m
BWC Factor = 0.155979 dB
Location: -7.5, -0.4, 3.7 mm

General Scans_580/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 41.2 dB
ABM1 comp = -13.6 dB A/m
BWC Factor = 0.155979 dB
Location: -6.7, 0.6, 3.7 mm



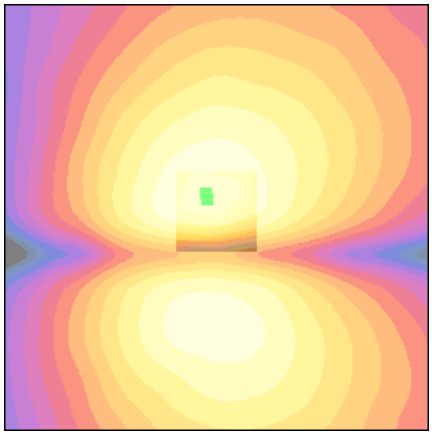
0 dB = 108.0

Test Laboratory: Comptest/Kyocera

FCC_E4233_TCoil_CELL 580 Y
Communication System: CDMA_Tri_BC0&10, Frequency: 820.5 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/13/2011
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 ± 1 deg C, Liquid T = 22.0 ± 1 deg C

General Scans_580/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 44.6 dB
ABM1 comp = -13.2 dB A/m
BWC Factor = 0.155979 dB
Location: 0.8, -5.4, 3.7 mm

General Scans_580/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 45.1 dB
ABM1 comp = -12.5 dB A/m
BWC Factor = 0.155979 dB
Location: 1, -6, 3.7 mm



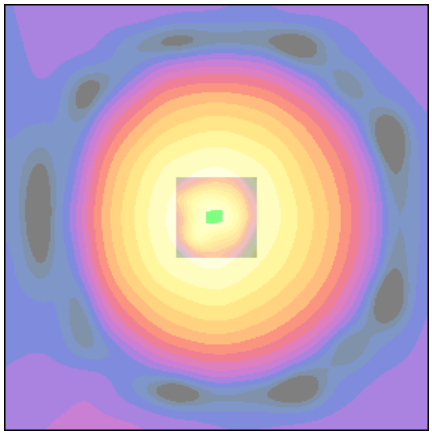
0 dB = 169.0

Test Laboratory: Comptest/Kyocera

FCC_E4233_TCoil_CELL 684 Z
Communication System: CDMA_Tri_BC0&10, Frequency: 823.1 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: $\sigma = 0$ mho/m, $\varepsilon_r = 1$; $\rho = 0$ kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/13/2011
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 ± 1 deg C, Liquid T = 22.0 ± 1 deg C

General Scans_684/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.4 dB
ABM1 comp = -4.74 dB A/m
BWC Factor = 0.155979 dB
Location: 0.4, 0, 3.7 mm

General Scans_684/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.7 dB
ABM1 comp = -4.74 dB A/m
BWC Factor = 0.155979 dB
Location: 0, -0.2, 3.7 mm



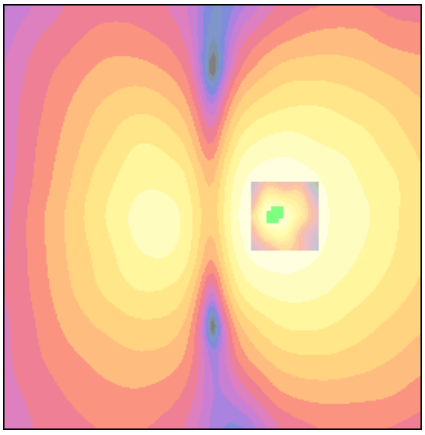
0 dB = 262.4

Test Laboratory: Comptest/Kyocera

FCC_E4233_TCoil_CELL 684 X
Communication System: CDMA_Tri_BC0&10, Frequency: 823.1 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/13/2011
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 ± 1 deg C, Liquid T = 22.0 ± 1 deg C

General Scans_684/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 40.6 dB
ABM1 comp = -14.1 dB A/m
BWC Factor = 0.155979 dB
Location: -7.5, -0.4, 3.7 mm

General Scans_684/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 41.1 dB
ABM1 comp = -13.5 dB A/m
BWC Factor = 0.155979 dB
Location: -6.9, 0, 3.7 mm



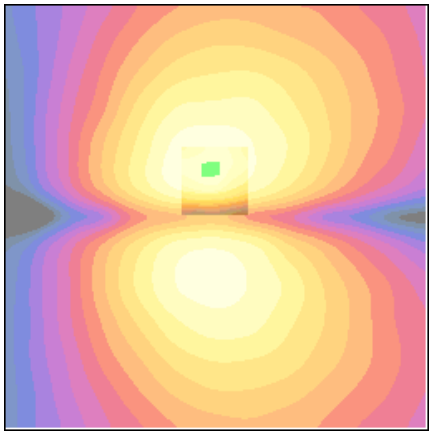
0 dB = 106.6

Test Laboratory: Comptest/Kyocera

FCC_E4233_TCoil_CELL 684 Y
Communication System: CDMA_Tri_BC0&10, Frequency: 823.1 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/13/2011
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 ± 1 deg C, Liquid T = 22.0 ± 1 deg C

General Scans_684/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 44.8 dB
ABM1 comp = -12.8 dB A/m
BWC Factor = 0.155979 dB
Location: 0.8, -5.4, 3.7 mm

General Scans_684/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 45.1 dB
ABM1 comp = -12.6 dB A/m
BWC Factor = 0.155979 dB
Location: 0.2, -5.6, 3.7 mm



0 dB = 174.0

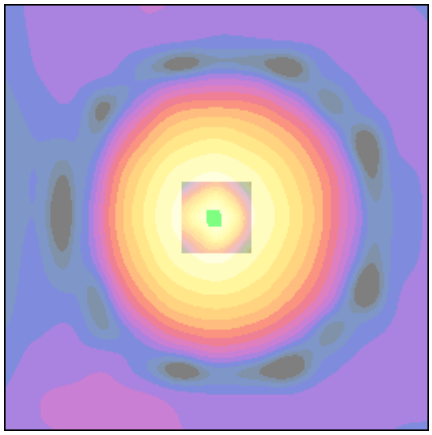
CELL BC-0

Test Laboratory: Comptest/Kyocera

FCC_E4233_TCoil_CELL 1013 Z
Communication System: CDMA_Tri_BC0&10, Frequency: 824.7 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/13/2011
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 1 deg C, Liquid T = 22.0 1 deg C

General Scans_1013/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.3 dB
ABM1 comp = -5.10 dB A/m
BWC Factor = 0.155979 dB
Location: 0.4, 0, 3.7 mm

General Scans_1013/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.6 dB
ABM1 comp = -4.80 dB A/m
BWC Factor = 0.155979 dB
Location: 0.2, 0.2, 3.7 mm



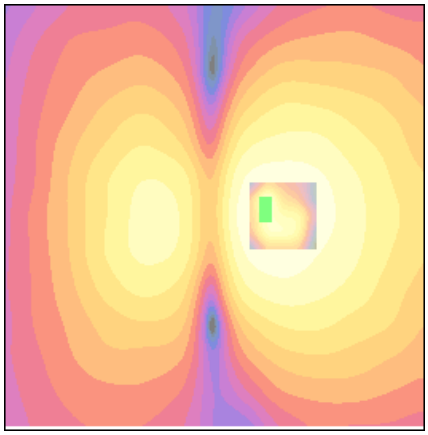
0 dB = 259.0

Test Laboratory: Comptest/Kyocera

FCC_E4233_TCoil_CELL 1013 X
Communication System: CDMA_Tri_BC0&10, Frequency: 824.7 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: $\sigma = 0$ mho/m, $\varepsilon_r = 1$; $\rho = 0$ kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/13/2011
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 ± 1 deg C, Liquid T = 22.0 ± 1 deg C

General Scans_1013/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 40.5 dB
ABM1 comp = -13.9 dB A/m
BWC Factor = 0.155979 dB
Location: -6.2, 0, 3.7 mm

General Scans_1013/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 41.0 dB
ABM1 comp = -13.6 dB A/m
BWC Factor = 0.155979 dB
Location: -6.3, -1.6, 3.7 mm



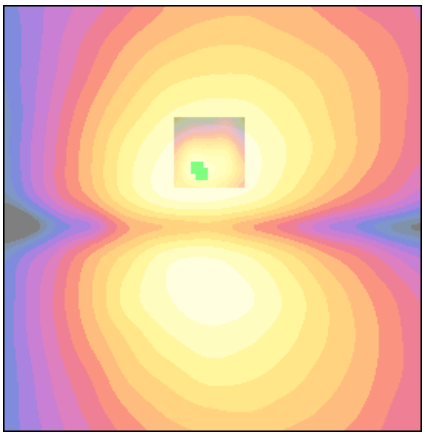
0 dB = 106.5

Test Laboratory: Comptest/Kyocera

FCC_E4233_TCoil_CELL 1013 Y
Communication System: CDMA_Tri_BC0&10, Frequency: 824.7 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/13/2011
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 ± 1 deg C, Liquid T = 22.0 ± 1 deg C

General Scans_1013/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 44.5 dB
ABM1 comp = -13.2 dB A/m
BWC Factor = 0.155979 dB
Location: 0.8, -5.8, 3.7 mm

General Scans_1013/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 45.2 dB
ABM1 comp = -12.3 dB A/m
BWC Factor = 0.155979 dB
Location: 1.4, -6.5, 3.7 mm



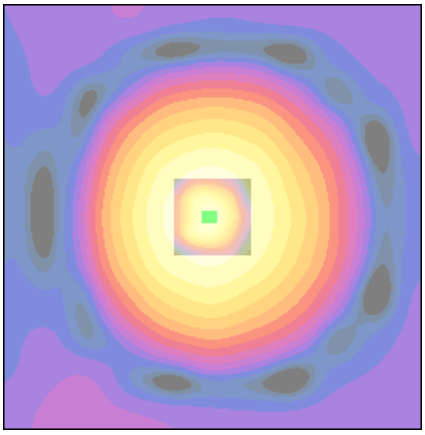
0 dB = 167.7

Test Laboratory: Comptest/Kyocera

FCC_E4233_TCoil_CELL 384 Z
Communication System: CDMA_Tri_BC0&10, Frequency: 836.52 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: $\sigma = 0$ mho/m, $\varepsilon_r = 1$; $\rho = 0$ kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/13/2011
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 ± 1 deg C, Liquid T = 22.0 ± 1 deg C

General Scans_384/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.2 dB
ABM1 comp = -4.98 dB A/m
BWC Factor = 0.155979 dB
Location: 0.4, 0, 3.7 mm

General Scans_384/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.8 dB
ABM1 comp = -4.73 dB A/m
BWC Factor = 0.155979 dB
Location: 0.2, 0, 3.7 mm



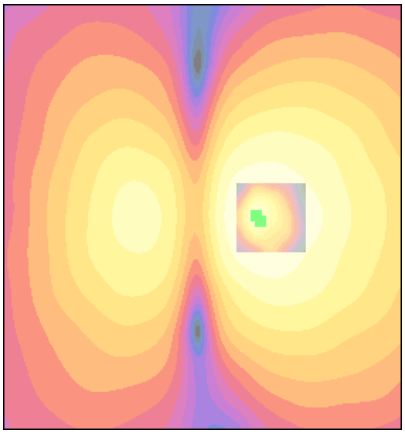
0 dB = 256.2

Test Laboratory: Comptest/Kyocera

FCC_E4233_TCoil_CELL 384 X
Communication System: CDMA_Tri_BC0&10, Frequency: 836.52 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/13/2011
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 ± 1 deg C, Liquid T = 22.0 ± 1 deg C

General Scans_384/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 41.1 dB
ABM1 comp = -14.0 dB A/m
BWC Factor = 0.155979 dB
Location: -7.1, 0.4, 3.7 mm

General Scans_384/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 41.6 dB
ABM1 comp = -13.4 dB A/m
BWC Factor = 0.155979 dB
Location: -6.5, -0.2, 3.7 mm



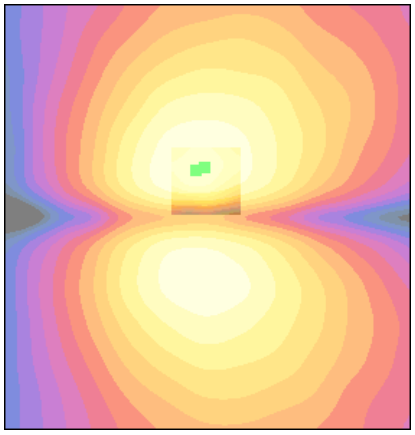
0 dB = 113.7

Test Laboratory: Comptest/Kyocera

FCC_E4233_TCoil_CELL 384 Y
Communication System: CDMA_Tri_BC0&10, Frequency: 836.52 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: $\sigma = 0$ mho/m, $\varepsilon_r = 1$; $\rho = 0$ kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/13/2011
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 ± 1 deg C, Liquid T = 22.0 ± 1 deg C

General Scans_384/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 44.5 dB
ABM1 comp = -13.0 dB A/m
BWC Factor = 0.155979 dB
Location: 1.3, -5.4, 3.7 mm

General Scans_384/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 45.1 dB
ABM1 comp = -12.7 dB A/m
BWC Factor = 0.155979 dB
Location: 0.2, -5.8, 3.7 mm



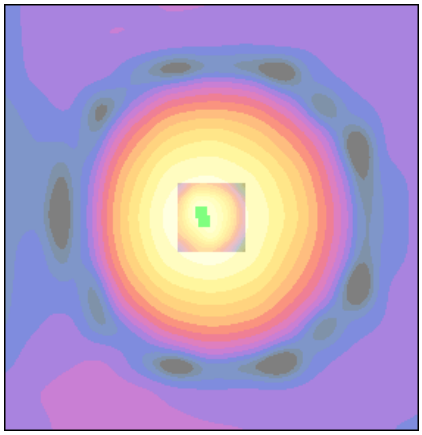
0 dB = 167.0

Test Laboratory: Comptest/Kyocera

FCC_E4233_TCoil_CELL 777 Z
Communication System: CDMA_Tri_BC0&10, Frequency: 848.31 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: $\sigma = 0$ mho/m, $\varepsilon_r = 1$; $\rho = 0$ kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/13/2011
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 ± 1 deg C, Liquid T = 22.0 ± 1 deg C

General Scans_777/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 47.8 dB
ABM1 comp = -5.16 dB A/m
BWC Factor = 0.155979 dB
Location: 0.8, 0.4, 3.7 mm

General Scans_777/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.4 dB
ABM1 comp = -4.69 dB A/m
BWC Factor = 0.155979 dB
Location: 1.2, -0.6, 3.7 mm



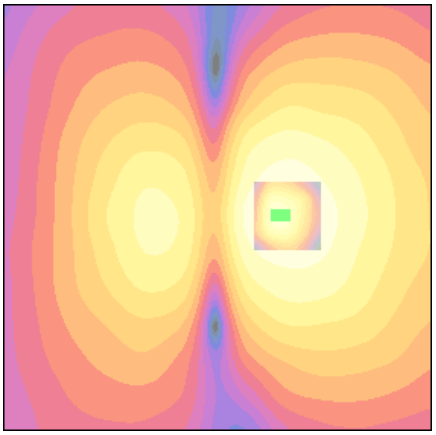
0 dB = 244.5

Test Laboratory: Comptest/Kyocera

FCC_E4233_TCoil_CELL 777 X
Communication System: CDMA_Tri_BC0&10, Frequency: 848.31 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/13/2011
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 ± 1 deg C, Liquid T = 22.0 ± 1 deg C

General Scans_777/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 40.9 dB
ABM1 comp = -14.1 dB A/m
BWC Factor = 0.155979 dB
Location: -7.9, 0, 3.7 mm

General Scans_777/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 40.8 dB
ABM1 comp = -13.9 dB A/m
BWC Factor = 0.155979 dB
Location: -7.1, 0, 3.7 mm



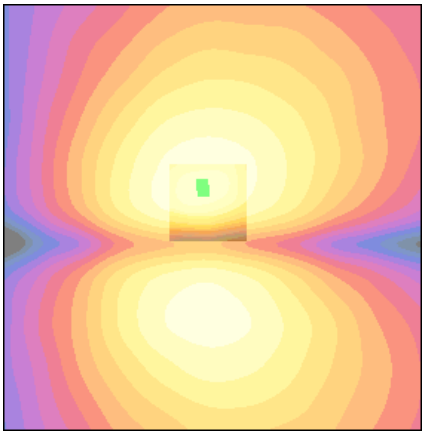
0 dB = 111.2

Test Laboratory: Comptest/Kyocera

FCC_E4210_TCoil_CELL 777 Y
Communication System: CDMA_Tri_BC0&10, Frequency: 848.31 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/13/2011
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 ± 1 deg C, Liquid T = 22.0 ± 1 deg C

General Scans_777/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 45.0 dB
ABM1 comp = -12.7 dB A/m
BWC Factor = 0.155979 dB
Location: 0.4, -5.4, 3.7 mm

General Scans_777/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 45.3 dB
ABM1 comp = -12.3 dB A/m
BWC Factor = 0.155979 dB
Location: 0.6, -6, 3.7 mm



0 dB = 177.5

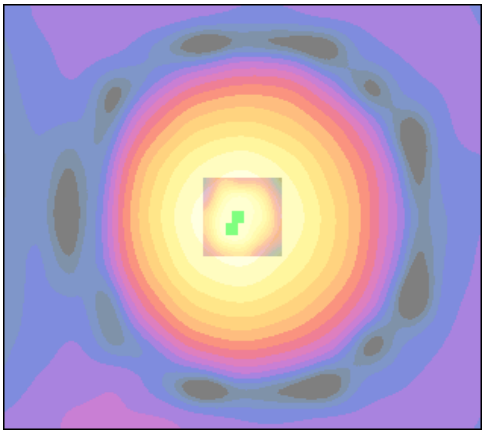
PCS

Test Laboratory: Comptest/Kyocera

FCC_E4233_TCoil_PCS_25 Z
Communication System: CDMA-1900, Frequency: 1851.25 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/13/2011
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 ± 1 deg C, Liquid T = 22.0 ± 1 deg C

General Scans_25/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 49.1 dB
ABM1 comp = -4.57 dB A/m
BWC Factor = 0.155979 dB
Location: 0.4, 0, 3.7 mm

General Scans_25/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.5 dB
ABM1 comp = -5.00 dB A/m
BWC Factor = 0.155979 dB
Location: 1, 1.2, 3.7 mm



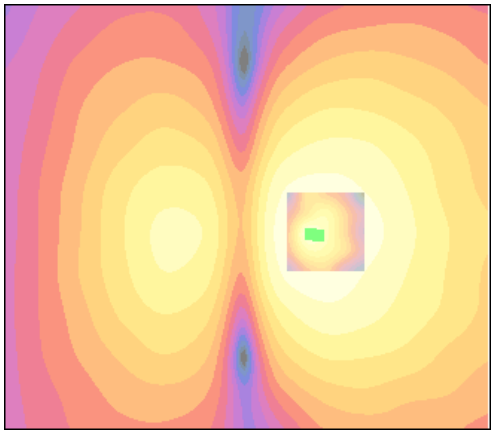
0 dB = 283.8

Test Laboratory: Comptest/Kyocera

FCC_E4233_TCoil_PCS_25 X
Communication System: CDMA-1900, Frequency: 1851.25 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/13/2011
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 ± 1 deg C, Liquid T = 22.0 ± 1 deg C

General Scans_25/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 40.8 dB
ABM1 comp = -13.9 dB A/m
BWC Factor = 0.155979 dB
Location: -7.5, 0.4, 3.7 mm

General Scans_25/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 40.8 dB
ABM1 comp = -13.5 dB A/m
BWC Factor = 0.155979 dB
Location: -6.7, 0.2, 3.7 mm



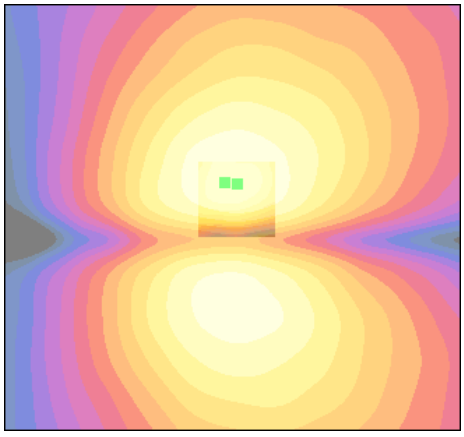
0 dB = 109.6

Test Laboratory: Comptest/Kyocera

FCC_E4233_TCoil_PCS_25 Y
Communication System: CDMA-1900, Frequency: 1851.25 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/13/2011
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 1 deg C, Liquid T = 22.0 1 deg C

General Scans_25/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 44.7 dB
ABM1 comp = -13.1 dB A/m
BWC Factor = 0.155979 dB
Location: 0, -5.8, 3.7 mm

General Scans_25/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 45.0 dB
ABM1 comp = -12.6 dB A/m
BWC Factor = 0.155979 dB
Location: 1.2, -6, 3.7 mm



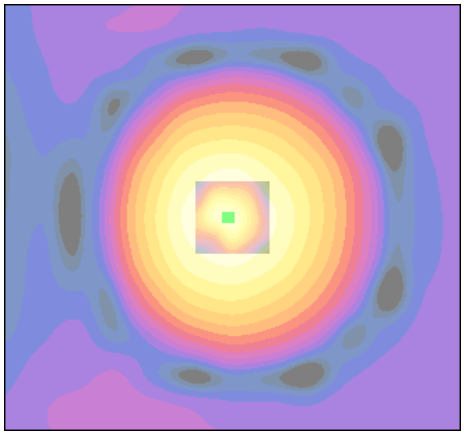
0 dB = 172.5

Test Laboratory: Comptest/Kyocera

FCC_E4233_TCoil_PCS_600 Z
Communication System: CDMA-1900, Frequency: 1880 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/13/2011
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 ± 1 deg C, Liquid T = 22.0 ± 1 deg C

General Scans_600/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 47.9 dB
ABM1 comp = -5.64 dB A/m
BWC Factor = 0.155979 dB
Location: 0.4, 0, 3.7 mm

General Scans_600/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.9 dB
ABM1 comp = -4.53 dB A/m
BWC Factor = 0.155979 dB
Location: 0.6, 0, 3.7 mm



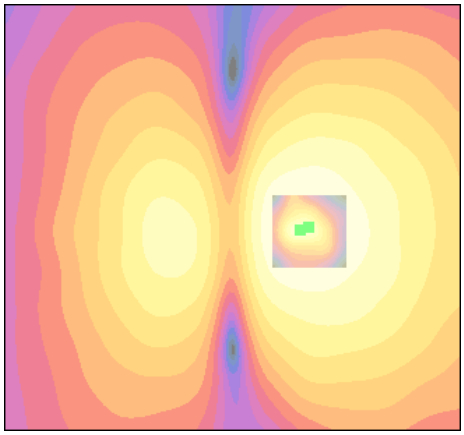
0 dB = 247.2

Test Laboratory: Comptest/Kyocera

FCC_E4233_TCoil_PCS_600 X
Communication System: CDMA-1900, Frequency: 1880 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/13/2011
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 ± 1 deg C, Liquid T = 22.0 ± 1 deg C

General Scans_600/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 40.2 dB
ABM1 comp = -14.6 dB A/m
BWC Factor = 0.155979 dB
Location: -8.3, -0.4, 3.7 mm

General Scans_600/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 41.1 dB
ABM1 comp = -13.5 dB A/m
BWC Factor = 0.155979 dB
Location: -7.3, -0.2, 3.7 mm



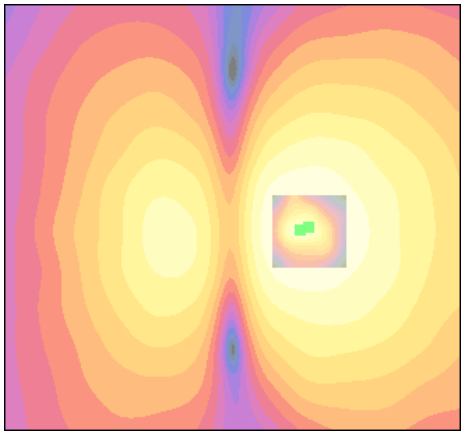
0 dB = 101.9

Test Laboratory: Comptest/Kyocera

FCC_E4233_TCoil_PCS_600 Y
Communication System: CDMA-1900, Frequency: 1880 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/13/2011
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 ± 1 deg C, Liquid T = 22.0 ± 1 deg C

General Scans_600/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 40.2 dB
ABM1 comp = -14.6 dB A/m
BWC Factor = 0.155979 dB
Location: -8.3, -0.4, 3.7 mm

General Scans_600/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 41.1 dB
ABM1 comp = -13.5 dB A/m
BWC Factor = 0.155979 dB
Location: -7.3, -0.2, 3.7 mm



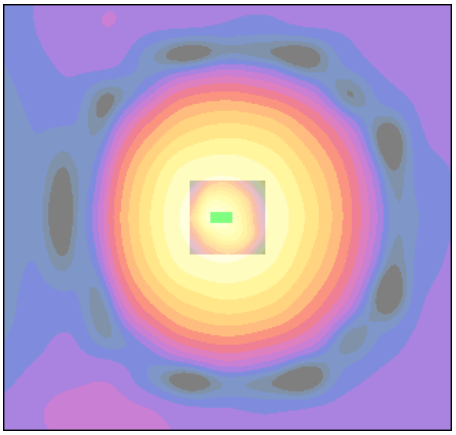
0 dB = 101.9

Test Laboratory: Comptest/Kyocera

FCC_E4233_TCoil_PCS_1175 Z
Communication System: CDMA-1900, Frequency: 1908.75 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/13/2011
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 ± 1 deg C, Liquid T = 22.0 ± 1 deg C

General Scans_1175/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.2 dB
ABM1 comp = -4.99 dB A/m
BWC Factor = 0.155979 dB
Location: 0, 0, 3.7 mm

General Scans_1175/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.3 dB
ABM1 comp = -4.91 dB A/m
BWC Factor = 0.155979 dB
Location: 1.2, 0, 3.7 mm



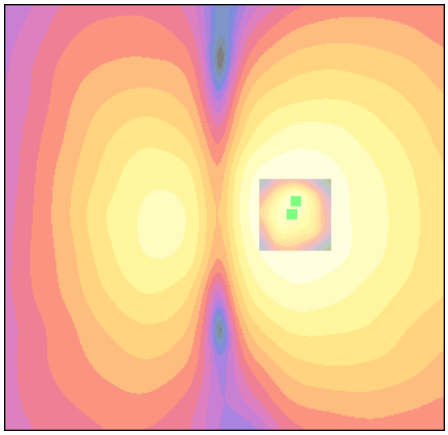
0 dB = 256.2

Test Laboratory: Comptest/Kyocera

FCC_E4233_TCoil_PCS_1175 X
Communication System: CDMA-1900, Frequency: 1908.75 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/13/2011
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 ± 1 deg C, Liquid T = 22.0 ± 1 deg C

General Scans_1175/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 39.2 dB
ABM1 comp = -14.8 dB A/m
BWC Factor = 0.155979 dB
Location: -7.9, 0, 3.7 mm

General Scans_1175/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 39.9 dB
ABM1 comp = -14.3 dB A/m
BWC Factor = 0.155979 dB
Location: -8.3, -1.6, 3.7 mm



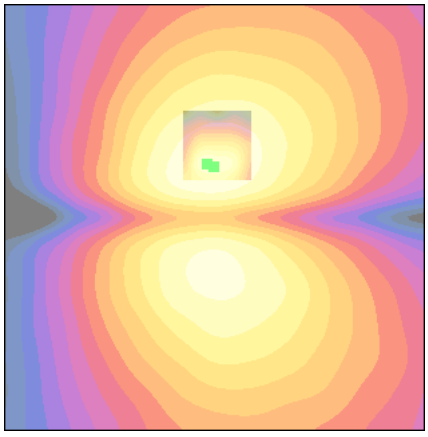
0 dB = 91.1

Test Laboratory: Comptest/Kyocera

FCC_E4233_TCoil_PCS_1175 Y
Communication System: CDMA-1900, Frequency: 1908.75 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/13/2011
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 ± 1 deg C, Liquid T = 22.0 ± 1 deg C

General Scans_1175/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 44.8 dB
ABM1 comp = -12.7 dB A/m
BWC Factor = 0.155979 dB
Location: 0.4, -5.8, 3.7 mm

General Scans_1175/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 44.9 dB
ABM1 comp = -12.4 dB A/m
BWC Factor = 0.155979 dB
Location: 1.2, -6.1, 3.7 mm



0 dB = 173.8